

# PRODUCT / PROCESS CHANGE NOTIFICATION

## 1. PCN basic data

|                      |                                                                                                                        |
|----------------------|------------------------------------------------------------------------------------------------------------------------|
| 1.1 Company          |  STMicroelectronics International N.V |
| 1.2 PCN No.          | EMBEDDED PROCESSING/26/16130                                                                                           |
| 1.3 Title of PCN     | STM32U375x and STM32U385x - product enhancement                                                                        |
| 1.4 Product Category | STM32U375x and STM32U385x                                                                                              |
| 1.5 Issue date       | 2026-08-31                                                                                                             |

## 2. PCN Team

|                           |                          |
|---------------------------|--------------------------|
| 2.1 Contact supplier      |                          |
| 2.1.1 Name                | ROBERTSON HEATHER        |
| 2.1.2 Phone               | +1 8475853058            |
| 2.1.3 Email               | heather.robertson@st.com |
| 2.2 Change responsibility |                          |
| 2.2.1 Product Manager     | Patrick AIDOUNE          |
| 2.1.2 Marketing Manager   | Marie TOURNUT            |
| 2.1.3 Quality Manager     | Pascal NARCHE            |

## 3. Change

|                          |                                                                                                                        |                            |
|--------------------------|------------------------------------------------------------------------------------------------------------------------|----------------------------|
| 3.1 Category             | 3.2 Type of change                                                                                                     | 3.3 Manufacturing Location |
| General Product & Design | Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix | TSMC (Taiwan)              |

## 4. Description of change

|                                                                                       | Old                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                | New                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                |
|---------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 4.1 Description                                                                       | <p>STM32U3 - (revision Y) product shows some limitations :</p> <ul style="list-style-type: none"> <li>- Retained SRAMs might be corrupted after Stop 1 mode or after reset.</li> <li>- LSE in bypass mode may not be functional.</li> <li>- Over-consumption from VDD when VDDA is lower than VDD.</li> <li>- TSC is partially not functional on PA15 and PB15.</li> <li>- Invalid DAC output voltage by DAC kernel clock setting.</li> </ul> <p>as described in Errata Sheet ES0626 - Rev 2.1 – February 2026</p> | <p>STM32U3 - (revision X) product enhancement fixes and limitations as listed below:</p> <ul style="list-style-type: none"> <li>- Retained SRAMs might be corrupted after Stop 1 mode or after reset - fixed.</li> <li>- LSE in bypass mode may not be functional - fixed</li> <li>- LSE bypass mode allowed only digital input - new limitation</li> <li>- Over-consumption from VDD when VDDA is lower than VDD- fixed.</li> <li>- TSC is partially not functional on PA15 and PB15 - fixed.</li> <li>- Invalid DAC output voltage by DAC kernel clock setting - fixed.</li> <li>- SRAM1PD and SRAM2PD bits of PWR_CR1 can't be used to power down SRAMs – new limitation.</li> <li>- Key wrap and SFI RSS features may not be functional in specific environmental conditions - fixed</li> </ul> <p>As described in Errata Sheet ES0626 - Rev 3 – July 2026</p> |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | Current STM32U375x and STM32U385x (Revision Y) product has limitations described in Errata Sheet ES0626                                                                                                                                                                                                                                                                                                                                                                                                            |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                    |

## 5. Reason / motivation for change

|                      |                                                                                                |
|----------------------|------------------------------------------------------------------------------------------------|
| 5.1 Motivation       | Improvements was implemented to increase robustness, performances and quality of our products. |
| 5.2 Customer Benefit | SERVICE IMPROVEMENT                                                                            |

## 6. Marking of parts / traceability of change

|                 |                                                                                                        |
|-----------------|--------------------------------------------------------------------------------------------------------|
| 6.1 Description | Traceability ensured by ST internal tools.<br>Die revision changes from "Y" to "X" on Package Marking. |
|-----------------|--------------------------------------------------------------------------------------------------------|

| 7. Timing / schedule                |              |
|-------------------------------------|--------------|
| 7.1 Date of qualification results   | 2026-10-20   |
| 7.2 Intended start of delivery      | 2026-11-18   |
| 7.3 Qualification sample available? | Upon Request |

| 8. Qualification / Validation                      |                                                                                            |            |            |
|----------------------------------------------------|--------------------------------------------------------------------------------------------|------------|------------|
| 8.1 Description                                    | 16130 MDRF-GPAM RER2206 - PCN16130 STM32U375x STM32U385x - Die 454_X cut1.3 - Rel plan.pdf |            |            |
| 8.2 Qualification report and qualification results | Available (see attachment)                                                                 | Issue Date | 2026-08-31 |

| 9. Attachments (additional documentations)                                                                                                                  |
|-------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 16130 Public product.pdf<br>16130 MDRF-GPAM RER2206 - PCN16130 STM32U375x STM32U385x - Die 454_X cut1.3 - Rel plan.pdf<br>16130 _Additional information.pdf |

| 10. Affected parts      |                         |                          |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current           |                         | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No  |
|                         | STM32U375CET6           |                          |
|                         | STM32U375CET6Q          |                          |
|                         | STM32U375CEU6           |                          |
|                         | STM32U375CGT6           |                          |
|                         | STM32U375CGT6Q          |                          |
|                         | STM32U375CGU6           |                          |
|                         | STM32U375CGU6Q          |                          |
|                         | STM32U375CGY6QTR        |                          |
|                         | STM32U375KEU6           |                          |
|                         | STM32U375KGU6           |                          |
|                         | STM32U375REI6Q          |                          |
|                         | STM32U375RET6           |                          |
|                         | STM32U375REY6QTR        |                          |
|                         | STM32U375RGI6           |                          |
|                         | STM32U375RGI6Q          |                          |
|                         | STM32U375RGT6           |                          |
|                         | STM32U375RGT6Q          |                          |
|                         | STM32U375RGY6GTR        |                          |
|                         | STM32U375RGY6QTR        |                          |
|                         | STM32U375VEI6           |                          |
|                         | STM32U375VET6           |                          |
|                         | STM32U375VGI6Q          |                          |
|                         | STM32U375VGT6           |                          |
|                         | STM32U375VGT6Q          |                          |
|                         | STM32U385CGT6           |                          |
|                         | STM32U385CGT6Q          |                          |
|                         | STM32U385CGU6           |                          |
|                         | STM32U385CGU6Q          |                          |
|                         | STM32U385CGY6QTR        |                          |
|                         | STM32U385KGU6           |                          |
|                         | STM32U385RGI6           |                          |
|                         | STM32U385RGI6Q          |                          |
|                         | STM32U385RGT6           |                          |
|                         | STM32U385RGT6Q          |                          |

|  |                  |  |
|--|------------------|--|
|  | STM32U385RGT7    |  |
|  | STM32U385RGY6GTR |  |
|  | STM32U385RGY6QTR |  |
|  | STM32U385VGI6    |  |
|  | STM32U385VGI6Q   |  |
|  | STM32U385VGT6    |  |
|  | STM32U385VGT6Q   |  |

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